

**Thyristor Module****Features**

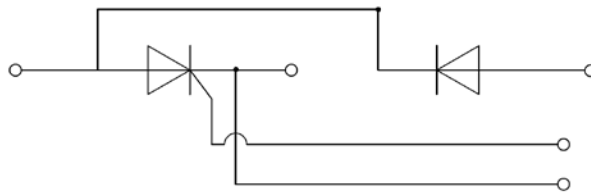
- Half-bridge SCR configuration integrated in a single package
- With high thermal conductivity DBC as the Insulation
- Welding by vacuum welding technology, which provide high reliability

Product Summary

Parameter	Value	Unit
V_{RRM}	1600	V
$I_{T(AV)}$ (@ $T_C = 85^\circ\text{C}$)	250	A
I_{TSM} (@ $t_p = 10\text{ms}$)	8300	A
$V_T(\text{Max})$	1.80	V

Applications

- Temperature control
- Light control system
- DC motor

**Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)**

Parameter	Conditions	Symbol	Values	Unit
Repetitive peak off-state voltage	$T_{vj} = 25^\circ\text{C}$	V_{DRM}	1600	V
Repetitive peak reverse voltage	$T_{vj} = 25^\circ\text{C}$	V_{RRM}	1600	V
Non-repetitive peak off-state voltage	$T_{vj} = 25^\circ\text{C}$	V_{DSM}	1700	V
Non-repetitive peak reverse voltage	$T_{vj} = 25^\circ\text{C}$	V_{RSM}	1700	V
Average forward current	$T_C = 85^\circ\text{C}$	$I_{T(AV)}$	250	A
Forward surge current	$t_p=10\text{ms } V_R=0.6V_{RRM}$	I_{TSM}	8300	A
I^2t value for fusing		I^2t	344450	A^2s
Critical rate of rise of on-state current	$I_G=2 \times I_{GT}$	di/dt	150	$\text{A}/\mu\text{s}$
RMS isolation voltage	A.C 50Hz(1s/1min)	V_{ISO}	3600/3000	V
Junction temperature range		T_J	-40 ~ +125	$^\circ\text{C}$
Storage temperature range		T_{stg}	-40 ~ +125	$^\circ\text{C}$

Electrical Characteristics (@ $T_c = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Peak forward voltage	$I_T=750\text{A}$, $t_P=380\mu\text{s}$	V_T			1.80	V
Repetitive peak off-state current	$V_D = V_{\text{DRM}}$, $T_c = 25^\circ\text{C}$	I_{DRM}			100	μA
	$V_D = V_{\text{DRM}}$, $T_c = 125^\circ\text{C}$				100	mA
Reverse leakage current	$V_R = V_{\text{RRM}}$, $T_c = 25^\circ\text{C}$	I_{RRM}			100	μA
	$V_R = V_{\text{RRM}}$, $T_c = 125^\circ\text{C}$				100	mA
Threshold voltage	For power loss calculation only $T_{vj} = 125^\circ\text{C}$,	V_{TO}			0.8	V
Dynamic resistance	$T_{vj} = 125^\circ\text{C}$,	r_T			1.05	$\text{m}\Omega$
Triggering gate current	$V_D=12\text{V}$ $R_L=30\Omega$	I_{GT}	20		150	mA
Holding current	$I_T=1\text{A}$	I_H			300	mA
Latching current	$I_G=1.2 I_{\text{GT}}$	I_L			400	mA
Triggering gate voltage	$V_D=12\text{V}$ $R_L=30\Omega$	V_{GT}			1.8	V
Non triggering gate voltage	$V_D=0.5V_{\text{DRM}}$ $T_{vj}=125^\circ\text{C}$	V_{GD}			0.25	V

Thermal Characteristics (@ $T_c = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Conditions	Symbol	Values			Unit
			Min.	Typ.	Max.	
Thermal resistance, junction to case	per chip	$R_{\text{th(j-c)}}$		0.11		$^\circ\text{C}/\text{W}$
Thermal resistance, case to heatsink	per chip	$R_{\text{th(c-s)}}$		0.06		$^\circ\text{C}/\text{W}$
Mounting torque	Module and heatsink fixed torque M5	M	4.25		5.75	N·m
	Electrode connection torque M8		7.65		10.35	N·m



Ordering Information

Device	Marking	Package	Weight	Inner Box	Pre Carton
JMT250KH16T3	JMT250KH16T3	T3	355±10g/PCS	3 PCS	27 PCS

Typical Electrical & Thermal Characteristics

FIG.1: Power dissipation vs. on-state current (per thyristor or diode)

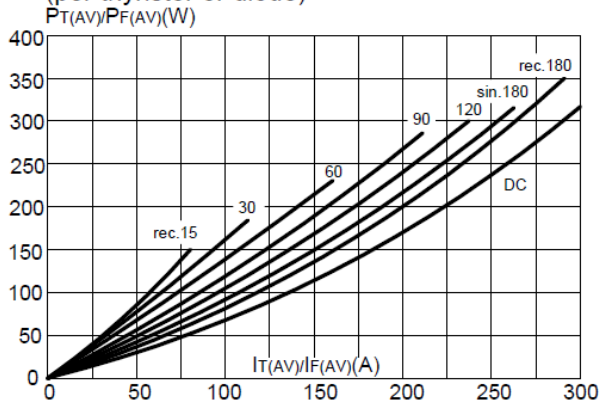


FIG.2: Maximum transient thermal impedance junction to case(per thyristor or diode)

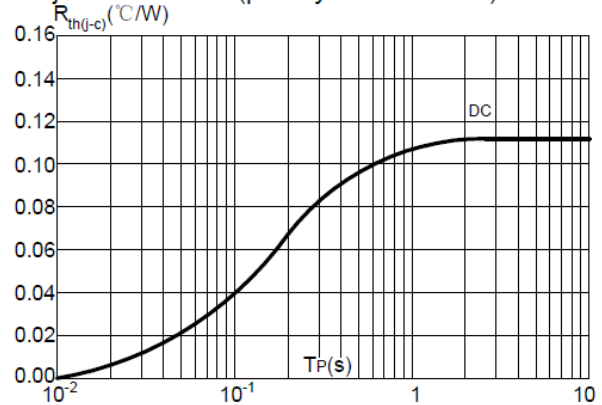


FIG.3: Forward characteristics (per thyristor or diode)

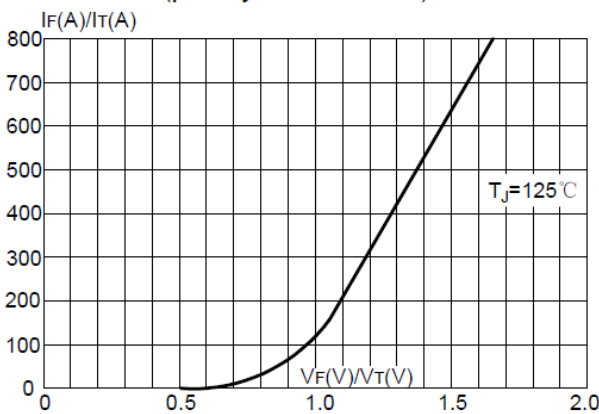
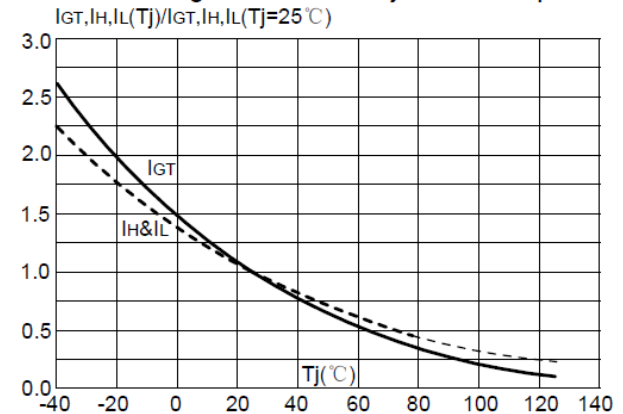
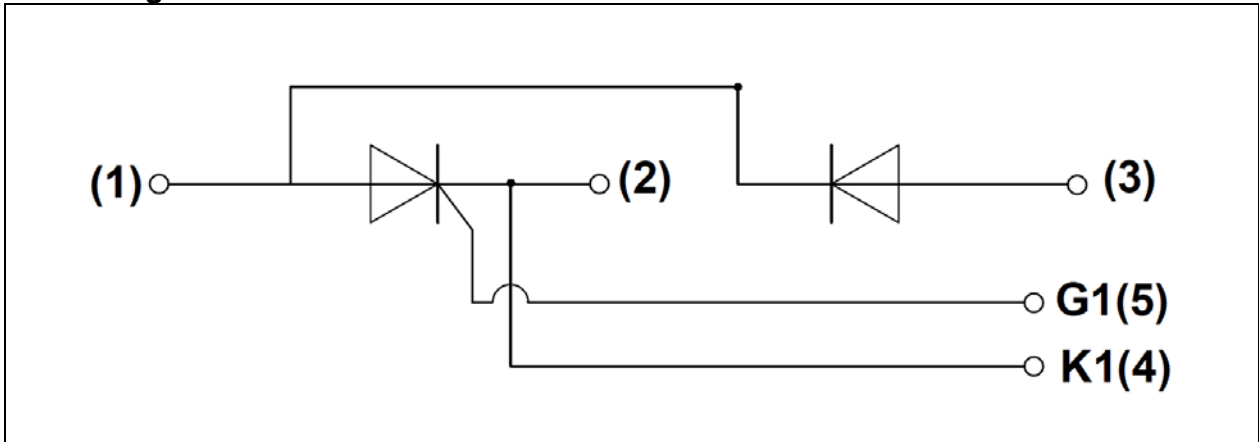


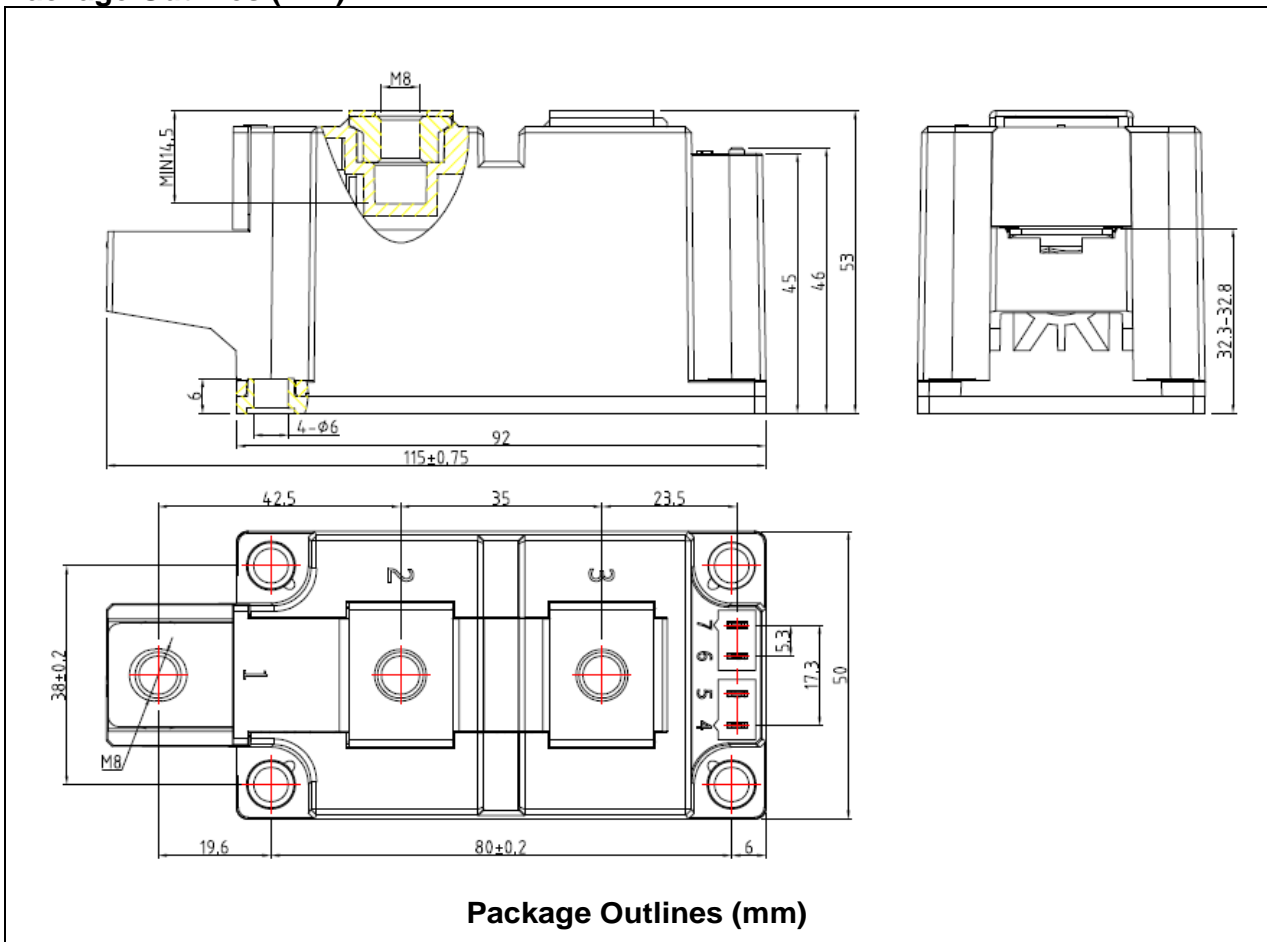
FIG.4: Relative variations of gate trigger current, holding current and latching current versus junction temperature



Circuit Diagram



Package Outlines (mm)



Package Outlines (mm)



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